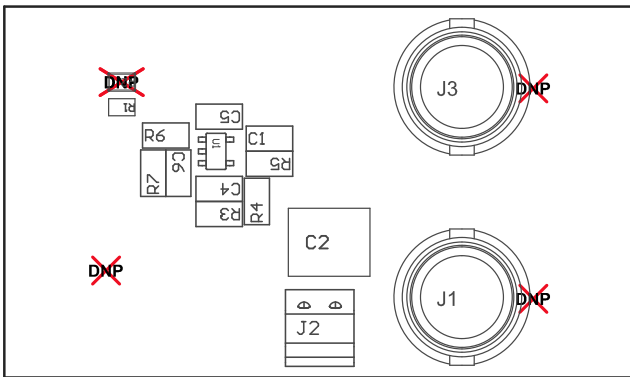


ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01636	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01636		
PLOT NAME = Top Assembly Drawing	GENERATED : 15-Jun-18 7:19:51 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01636	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01636		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 15-Jun-18 7:19:53 PM		TEXAS INSTRUMENTS

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